



Rework and Repair of Double Layer, Multilayer Printed Circuit Boards and Flexible



This Training is designed for Technicians with experience

One more day is recommended for less experienced employees.

Content :

- The Logical Approach to Repair Training
- Analysis and Definition of the Problem
- Defined the Procedures of Work
- Base Material of Substrate and Coatings
- Removing Conformal Coating
- Different Methods of Component Removal
- Different Methods of Component Removal on Large Thermal Mass Using Auxiliary Heat
- Wire Repair Method
- Flat Conductor Repair Method with Cir-Kit Conductors
- Repair of Lifted or Missing Pads
- Removal and Replacement of Eyelets, Rivets and Terminals
- Repairing a Burned or Missing Section of Circuit Board
- Repairing Multilayer Boards and Flex
- Refurbishing/Replating Repair or Worn Edge Connectors
- Modifications & Repair with Jumper wires
- Evaluation by the Standards IPC 7711/7721



At the end of the Training the student's will received:

- ✓ A training Handbook
- ✓ The Circuits that they assembled during the training
- ✓ A Certificate of our Company

The Training will be provided by highly skilled IPC Certified instructors (A-610, ANSI-J-STD-001, IPC 7711/7721)

Hand tools soldering station of new generation and microscope for each workbench
Circuits, Components and a Handbook are provided.

TEKTRO Centre Accrédité IPC

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IPC A-610,
IPC HWMA 620
ANSI-J-STD 001
IPC 7711/7721